

(1,00mm) .03937"

SAL1 SERIES



HIGH SPEED MICRO PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?SAL1

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Au or Sn over

50µ" (1,27µm) Ni

Operating Temp:

-55°C to +125°C

Current Rating:

2.3 A @ 80°C

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

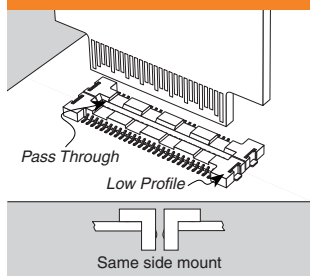
SMT Lead Coplanarity:

(0,10mm) .004" max



Mates with:
(1,60mm) .062" or
(2,40mm) .093" card

APPLICATIONS



Mount in pairs on same side or opposite sides for easy signal routing

(1,00mm) .03937" pitch

Variable mating card thickness

Large deflection BeCu contact

Surface Mount

Weld tab

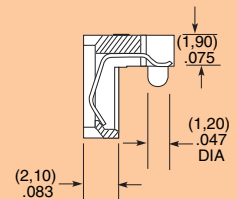
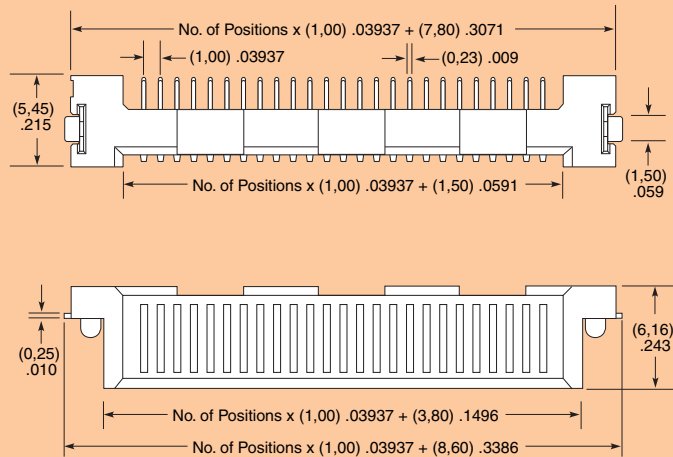
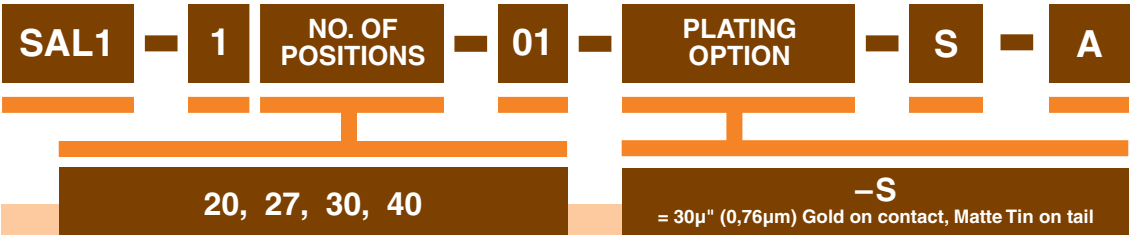
SATALink™
Compatible
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APPLICATION SPECIFIC OPTION

Heavy Gold plating available. Call Samtec.

1,65mm Stack Height	Rated @ 3dB Insertion Loss
Single-Ended Signaling	8.5 GHz / 17 Gbps
Differential Pair Signaling	9.0 GHz / 18 Gbps

Performance data for other stack heights and complete test data available at www.samtec.com?SAL1 or contact sig@samtec.com



Note: Other Gold plating options available. Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM